

INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification⁶:

G01R 31/316, 1/073

A1

(11) International Publication Number:

WO 98/11449

(43) International Publication Date:

19 March 1998 (19.03.98)

(21) International Application Number: PCT/US97/16264

(22) International Filing Date: 12 September 1997 (12.09.97)

(30) Priority Data:

60/026,088

13 September 1996 (13.09.96) US

(71) Applicant (for all designated States except US): INTERNATIONAL BUSINESS MACHINES CORPORATION
[US/US]; Old Orchard Road, Armonk, NY 10504 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): BEAMAN, Brian, Samuel
[US/US]; 104 Southwold Drive, Apex, NC 27502 (US). FOGEL, Keith, Edward [US/US]; 4 Lucs Lane, Mohegan Lake, NY 10547 (US). LAURO, Paul, Alfred [US/US]; Apartment D, 4 James Drive, Nanuet, NY 10954 (US). SHIH, Da-Yuan [US/US]; 16 Vervalen Drive, Poughkeepsie, NY 12603 (US).

(74) Agent: MORRIS, Daniel, P.; International Business Machines Corporation, Intellectual Property Law Dept., P.O. Box 218, Yorktown Heights, NY 10598 (US).

(81) Designated States: JP, US, European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE).

Published

With international search report.

(54) Title: WAFER SCALE HIGH DENSITY PROBE ASSEMBLY, APPARATUS FOR USE THEREOF AND METHODS OF FABRICATION THEREOF

(57) Abstract

A structure comprising: a substrate having a surface; a plurality of elongated electrical conductors extending away from said surface; each of said elongated electrical conductors having a first end affixed to said surface and a second end projecting away from said surface; there being a plurality of said second ends; a means for permitting each of said plurality of said second ends to move about reference positions.

